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- (54) Title:** FLEXIBLE CIRCUIT COVERFILM ADHESION ENHANCEMENT

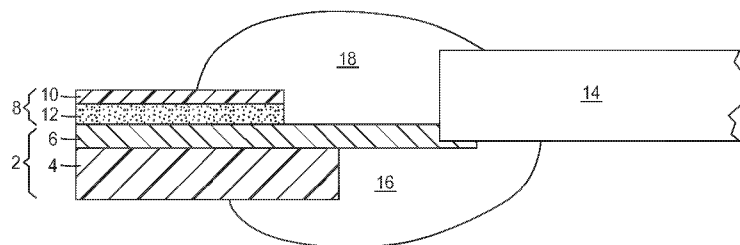


FIG. 1

- (57) Abstract:** Provided is a means of improving the adhesion between a flexible circuit coverfilm and an encapsulant material in an inkjet printer application.